# (Dot Matrix Liquid Crystal Graphic Display Column Driver)

# **Description**

The HD44102CH is a column (segment) driver for dot matrix liquid crystal graphic display systems, storing the display data transferred from a 4-bit or 8-bit microcomputer in the internal display RAM and generating dot matrix liquid crystal driving signals.

Each bit data of display RAM corresponds to on/off state of each dot of a liquid crystal display to provide more flexible than character display.

The HD44102CH is produced by the CMOS process. Therefore, the combination of HD44102CH with a CMOS microcontroller can complete portable battery-driven unit ntilizing the liquid crystal display's low power dissipation.

The combination of HD44102CH with the row (common) driver HD44103CH facilitates dot matrix liquid crystal graphic display system configuration.

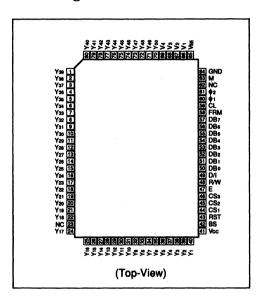
#### **Features**

- Dot matrix liquid crystal graphic display column driver incorporating display RAM
- Interfaces with 4-bit or 8-bit MPU
- RAM data directly displayed by internal display RAM

RAM bit data 1: On RAM bit data 0: Off

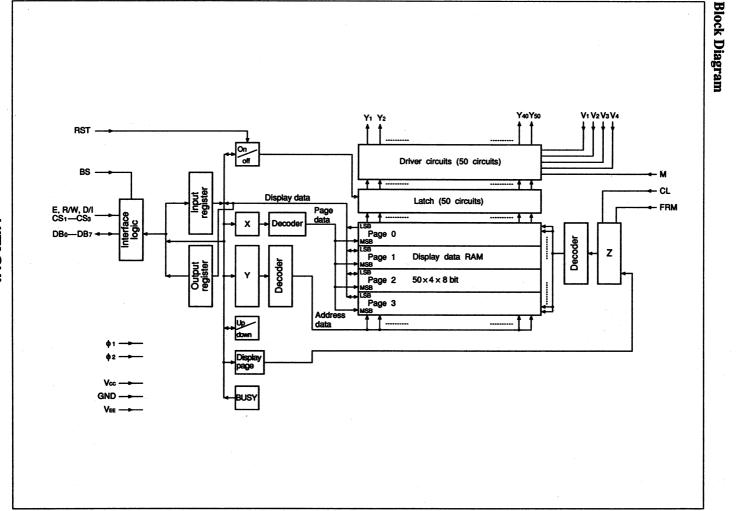
- Display RAM capacity: 50 × 8 × 4 (1600 bits)
- Internal liquid crystal display driver circuit (segment output): 50 segment signal drivers
- Duty factor (can be controlled by external input waveform)
  - Selectable duty factors: 1/8, 1/12, 1/16, 1/24, 1/32
- Wide range of instruction functions
  - Display Data Read/Write, Display On/Off, Set Address, Set Display
  - Start Page, Set Up/Down, Read Status
- Low power dissipation
- Power supplies:  $V_{CC}$  5 V  $\pm$  10%,  $V_{EE}$  0 to -5 V
- CMOS process

# Pin Arrangement



# **Ordering Information**

Type No.	Package
HD44102CH	80-pin plastic OFP(FP-80)
HD44102D	chip



# **Absolute Maximum Ratings**

Item	Symbol	Value	Unit	Notes	
Supply voltage (1)	V <sub>cc</sub>	-0.3 to +7.0	٧	1	
Supply voltage (2)	V <sub>EE</sub>	$V_{cc}$ -13.5 to $V_{cc}$ + 0.3	٧		
Input voltage (1)	V <sub>T1</sub>	-0.3 to V <sub>cc</sub> + 0.3	V	1, 2	
Input voltage (2) V <sub>12</sub>		$V_{\rm EE}$ -0.3 to $V_{\rm cc}$ + 0.3	٧	3	
Operating temperature	Topr	-20 to +75	°C		
Storage temperature	T <sub>stg</sub>	-55 to +125	°C		

Notes: 1. Referenced to GND = 0.

2. Applied to input terminals (except V1, V2, V3, and V4), and I/O common terminals.

3. Applied to terminals V1, V2, V3, and V4.

# **Electrical Characteristics**

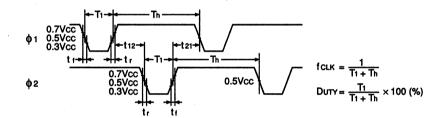
(
$$V_{\rm CC}$$
 = +5 V ±10%, GND = 0 V,  $V_{\rm EE}$  = 0 to -5.5 V, Ta = -20 to 75 °C) (Note 4)

Item	Symbol	Min	Тур	Max	Unit	Test condition	Notes
Input high voltage (CMOS)	V <sub>IHC</sub>	0.7 × V <sub>cc</sub>	-	V <sub>cc</sub>	٧		5
Input low voltage (CMOS)	V <sub>ILC</sub>	0	_	0.3 × V <sub>cc</sub>	٧		5
Input high voltage (TTL)	V <sub>IHT</sub>	2.0	_	V <sub>cc</sub>	٧		6
Input low voltage (TTL)	V <sub>ILT</sub>	0	_	+0.8	٧		6
Output high voltage	V <sub>oH</sub>	+3.5	_	_	٧	I <sub>OH</sub> = -250 μA	7
Output low voltage	V <sub>OL</sub>	_	_	+0.4	٧	I <sub>OL</sub> = +1.6 mA	7
Vi-Xj ON resistance	R <sub>on</sub>	_	_	7.5	kΩ	$V_{EE} = -5 \text{ V} \pm 10\%,$	
						Load current 100 μA	
Input leakage current (1)	l <sub>IL1</sub>	-1	-	1	μΑ	V <sub>IN</sub> = V <sub>CC</sub> to GND	8
Input leakage current (2)	l <sub>IL2</sub>	-2	_	2	μА	V <sub>IN</sub> = V <sub>CC</sub> to V <sub>EE</sub>	9
Operating frequency	f <sub>CLK</sub>	25	_	280	kHz	φ1, φ2 frequency	10
Dissipation current (1)	I <sub>cc1</sub>	_	_	100	μА	f <sub>clk</sub> = 200 kHz frame =	11
						65 Hz during display	
Dissipation current (2)	I <sub>CC2</sub>	_	_	500	μА	Access cycle 1 MHz	12
						at access	

Notes: 4. Specified within this range unless otherwise noted.

- 5. Applied to M, FRM, CL, BS, RST, φ1, φ2.
- 6. Applied to CS1 to CS3, E, D/I, R/W and DBO to DB7.
- 7. Applied to DB0 to DB7.
- Applied to input terminals, M, FRM,CL, BS, RST, φ1, φ2, CS1 to CS3, E, D/I and R/W, and I/O common terminals DB0 to DB7 at high impedance.
- 9. Applied to V1, V2, V3, and V4.
- 10. \$\phi1\$ and \$\phi2\$ AC characteristics.

	Symbol	Min	Тур	Max	Unit
Duty factor	Duty	20	25	30	%
Fall time	t,	-	_	100	ns
Rise time	t,	-	_	100	ns
Phase difference time	t <sub>12</sub>	0.8	-	_	μs
Phase difference time	t <sub>21</sub>	0.8	_	_	μs
$T_1 + T_h$		_	-	40	μs



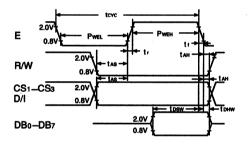
- 11. Measured by  $V_{cc}$  terminal at no output load, at 1/32 dury factor, and frame frequency of 65 Hz, in checker pattern display. Access from the CPU is stopped.
- 12. Measured by  $V_{\rm cc}$  terminal at no output load, 1/32 duty factor and frame frequency of 65 Hz.

# **Interface AC Characteristics**

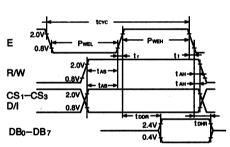
Symbol	Min	Тур	Max	Unit	Notes
t <sub>cyc</sub>	1000	_	_	ns	13, 14
P <sub>WEH</sub>	450	_	_	ns	13, 14
P <sub>weL</sub>	450	-	-	ns	13, 14
ţ,	_	-	25	ns	13, 14
t,	-	_	25	ns	13, 14
t <sub>AS</sub>	140	_	_	ns	13, 14
t <sub>AH</sub>	10	-		ns	13, 14
t <sub>bsw</sub>	200	_	_	ns	13
t <sub>DDR</sub>	_	_	320	ns	14, 15
t <sub>DHW</sub>	10	-	_	ns	13
t <sub>DHR</sub>	20	-	_	ns	14
	t <sub>CYC</sub> P <sub>WEH</sub> P <sub>WEL</sub> t <sub>r</sub> t <sub>t</sub> t <sub>AS</sub> t <sub>AH</sub> t <sub>DSW</sub> t <sub>DDR</sub>	t <sub>CYC</sub> 1000  P <sub>WEH</sub> 450  P <sub>WEL</sub> 450  t <sub>r</sub> -  t <sub>t</sub> -  t <sub>AS</sub> 140  t <sub>AH</sub> 10  t <sub>DDR</sub> -  t <sub>DHW</sub> 10	t <sub>CYC</sub> 1000 - P <sub>WEH</sub> 450 - P <sub>WEL</sub> 450 - t <sub>t</sub> t <sub>t</sub> t <sub>AS</sub> 140 - t <sub>DSW</sub> 200 - t <sub>DDR</sub> t <sub>DHW</sub> 10 -	t <sub>CYC</sub> 1000  P <sub>WEH</sub> 450  P <sub>WEL</sub> 450  t <sub>r</sub> - 25  t <sub>t</sub> 25  t <sub>AS</sub> 140  t <sub>DDR</sub> - 320  t <sub>DHW</sub> 10	t <sub>CYC</sub> 1000     -     -     ns       P <sub>WEH</sub> 450     -     -     ns       P <sub>WEL</sub> 450     -     -     ns       t <sub>r</sub> -     -     25     ns       t <sub>r</sub> -     -     25     ns       t <sub>AS</sub> 140     -     -     ns       t <sub>AH</sub> 10     -     -     ns       t <sub>DSW</sub> 200     -     -     ns       t <sub>DDR</sub> -     -     320     ns       t <sub>DHW</sub> 10     -     -     ns

Notes:

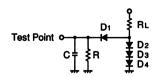
13. At CPU write



14. At CPU read



# 15. DB0 to DB7 load circuits



$$R_L = 2.4 \text{ k}\Omega$$

$$R = 11 k\Omega$$

C = 130 pF (including jig capacitance)

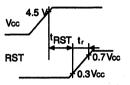
Diodes D<sub>1</sub> to D<sub>4</sub> are all 1S2074 (H)

Notes: 16. Display off at initial power up.

The HD44102CH can be placed in the display off state by setting terminal RST to low at initial power up.

No instruction other than the Read Status can be accepted while the RST is at the low level.

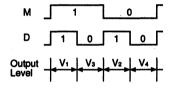
	Symbol	Min	Тур	Max	Unit	
Reset time	t <sub>est</sub>	1.0	_	_	μs	
Rise time	ţ,	_	-	200	ns	



# **Pin Description**

Pin Name	Pin Number	I/O	Function	
Y1 - Y50	50	0	Liquid crystal display drive output.	

Relationship among output level, M and display data (D):



CS1 - CS3 3

Chip select

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CS1	CS2	CS3	State
L	L	L	Non-selected
L	L	Н	Non-selected
L	Н	L	Non-selected
L	H	Н	Selected read/write enable
H	L	L	Selected write enable only
H	L	H	Selected write enable only
H	Н	L	Selected write enable only
Н	Н	Н	Selected read/write enable

Ε

1

Enable

At write (R/W = Low): Data of DB0 to DB7 is latched at the fall of E. At read (R/W = High): Data appears at DB0 to DB7 while E is at high level.

Pin Name	Pin Number	I/O	Function						
R/W	1	1	Read/Write R/W = High: Data appears at DB0 to DB7 and can be read by the CPU when E = high and CS2, CS3 = high. R/W = Low: DB0 to DB7 can accept input when CS2, CS3 = high or CS1 = high.						
D/I	1	I	Data/Instruction D/I = High: Indicates that the data of DB0 to DB7 is display data. D/I = Low: Indicates that the data of DB0 to DB7 is display control data.						
DB0-DB7	8	I/O	Data bus, three-state I/O common terminal						
			E R/W CS1 CS2 CS3 State of DB0 to DB7						
			H H * H H Output state						
			* L H * * Input state,						
			* L * H H High impedance						
			Others High impedance						
М	1	ı	Signal to convert liquid crystal display drive output to AC.						
CL	1	I	Display synchronous signal At the rise of CL signal, the liquid crystal display drive signal corresponding to display data appears.						
FRM	1	I	Display synchronous signal (frame signal)  This signal presets the 5-bit display line counter and synchronizes a common signal with the frame timing when the FRM signal becomes high.						
φ1, φ2	2	ı	2-phase clock signal for internal operation  The φ1 and φ 2 clocks are used to perform the operations (input/output of display data and execution of instructions) other than display.						
RST	1	1	Reset signal The display disappears and Y address counter is set in the up counter state by setting the RST signal to low level. After releasing reset, the display off state and up mode is held until the state is changed by the instruction.						
BS	1	ı	Bus select signal BS = Low: DB0 to DB7 operate for 8-bit length. BS = High: DB4 to DB7 are valid for 4-bit length only. 8-bit data is accessed twice in the high and low order.						
V1, V2, V3, V4	4		Power supply for liquid crystal display drive V1 and V2: Selection voltage V3 and V4: Non-selection voltage						

Pin Name	Pin Number	1/0	Function	
V <sub>cc</sub> GND V <sub>EE</sub>	3		Power supply V <sub>cc</sub> -GND: V <sub>cc</sub> -V <sub>ee</sub> :	Power supply for internal logic Power supply for liquid crystal display drive circuit logic

#### **Function of Each Block**

# **Interface Logic**

The HD44102CH can use the data bus in 4-bit or 8-bit word length to enable interface to a 4-bit or 8-bit CPU.

4 bit mode (BS = High)
 8-bit data is transferred twice for every 4 bits through the data bus when the BS signal is high.

The data bus uses the high order 4 bits (DB4 to DB7). First, the high order 4 bits (DB4 to DB7 in 8-bit data length) are transferred and then the low order 4 bits (DB0 to DB3 in 8-bit data length).

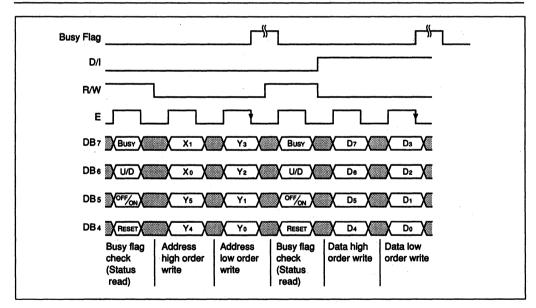


Figure 1 4-Bit Mode Timing

Note: Execute instructions other than status read in 4-bit length each. The busy flag is set at the fall of the second E signal. The status read is executed once. After the execution of the status read, the first 4 bits are considered the high order 4 bits. Therefore, if the busy flag is checked after the transfer of the high order 4 bits, retransfer data from the higher order bits. No busy check is required in the transfer between the high and low order bits.

#### 2. 8-bit mode (BS = Low)

If the BS signal is low, the 8 data bus lines (DB0 to DB7) are used for data transfer.

DB7: MSB (Most significant bit)
DB0: LSB (Least significant bit)

For AC timing, refer to note 12 to note 15 of "Electrical Characteristics".

#### Input Register

8-bit data is written into this register by the CPU. The instruction and display data are distinguished by the 8-bit data and D/I signal and then a given operation is performed. Data is received at the fall of the E signal when the CS is in the select state and R/W is in write state.

#### **Output Register**

The output register holds the data read from the display data RAM. After display data is read, the display data at the address now indicated is set in this output register. After that, the address is increased or decreased by 1. Therefore, when an address is set, the correct data doesn't appear at the read of the first display data. The data at a specified address appears at the second read of data (figure 2).

#### X, Y Address Counter

The X, Y address counter holds an address for reading/writing display data RAM. An address is set in it by the instruction. The Y address register is composed of a 50-bit up/down counter. The address is increased or decreased by 1 by the read/write operation of display data. The up/down mode can be determined by the instruction or RST signal. The Y address register counts by looping the values of 0 to 49. The X address register has no count function.

## Display On/Off Flip/Flop

This flip/flop is set to on/off state by the instruction or RST signal. In the off state, the latch of display data RAM output is held reset and the display data output is set to 0. Therefore, display disappears. In the on state, the display data appears according to the data in the RAM and is displayed. The display data in the RAM is independent of the display on/off.

## Up/Down Flip/Flop

This flip/flop determines the count mode of the Y address counter. In the up mode, the Y address register is increased by 1. 0 follows 49. In the down mode, the register is decreased by 1. 0 is followed by 49.

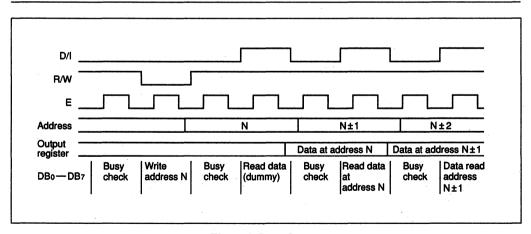


Figure 2 Data Output

#### Display Page Register

The display page register holds the 2-bit data that indicates a display start page. This value is preset to the high order 2 bits of the Z address counter by the FRM signal. This value indicates the value of the display RAM page displayed at the top of the screen.

#### **Busy Flag**

After an instruction other than status read is accepted, the busy flag is set during its effective period, and reset when the instruction is not effective (figure 3). The value can be read out on DB7 by the status read instruction.

The HD44102CH cannot accept any other instructions than the status read in the busy state. Make sure the busy flag is reset before issuing an instruction.

#### **Z Address Counter**

The Z address counter is a 5-bit counter that counts up at the fall of CL signal and generates an address for outputting the display data synchronized with the common signal. 0 is preset to the low order 3 bits and a display start page to the high order 2 bits by the FRM signal.

#### Latch

The display data from the display data RAM is latched at the rise of CL signal.

#### **Liquid Crystal Driver Circuit**

Each of 50 driver circuits is a multiplex circuit composed of 4 CMOS switches. The combination of display data from latchs and the M signal causes one of the 4 liquid crystal driver levels, V1, V2, V3 and V4 to be output.

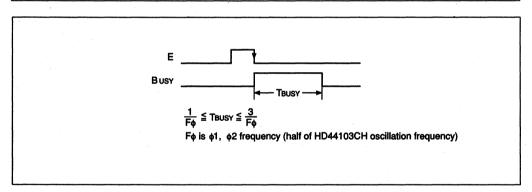


Figure 3 Busy Flag

# **Display RAM**

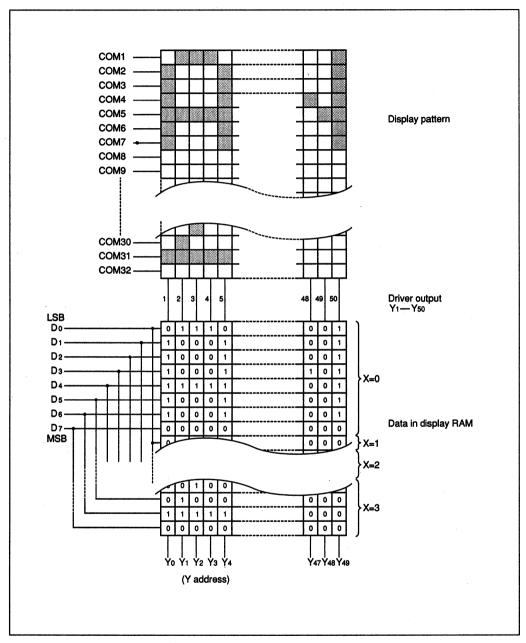


Figure 4 Relationship between Data in RAM and Display (Display start page 0, 1/32 duty)

# **Display Control Instructions**

# Read/Write Display Data

		MSB DB LSB							
R/W	D/I	7 6 5 4 3 2 1 0							
1	1	(Display data)							
	Read (CPU ← HD44102CH)								
0	1	(Display data)							
		Write (CPU →HD44102CH)							

Sends or receives data to or from the address of the display RAM specified in advance. However, a dummy read may be required for reading display data. Refer to the description of the output register in Function of Each Block.

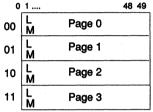
# Display On/Off

		М	SE	3		D	В			LSB	
R/W	D/I		7	6	5	4	3	2	1	0	
0	0		0	0	1	1	1	0	0	1	Display on
0	0		0	0	1	1	1	0	0	0	Display off

Turns the display on/off. RAM data is not affected.

# Set X/Y Address

		MSB DB LSB
R/W	D/I	7 6 5 4 3 2 1 0
0	0	0 0
0	0	0 1 Binary numbers of 0-49
0	0	1 0
0	0	1 1
		<u> </u>
		X address Y address (page) (address)
		Y address
	0 1.	48 49



Display Data RAM

# **Display Start Page**

		MSB		DB				LSB
R/W	D/I	7 6	5	4	3	2	1	0
0	0	0 0	1	1	1	1	1	0
		•••••	Re	efei	r to	figu	ıre	5 (a)
0	0	0 1	1	1	1	1	1	0
		•••••	R	əfei	r to	figu	ıre	5 (b)
0	0	1 0	1	1	1	1	1	0
			R	efe	r to	figu	ıre	5 (c)
0	0	11	1	1	1	1	1	0
		Disp	ay.	sta	rt p	age	•	
		•	R	efe	r to	fiau	ıre	5 (d)

Specifies the RAM page displayed at the top of the screen. Display is as shown in figure 4. When the display duty factor is more than 1/32 (For example, 1/

24, 1/16), display begins at a page specified by the display start page only by the number of lines.

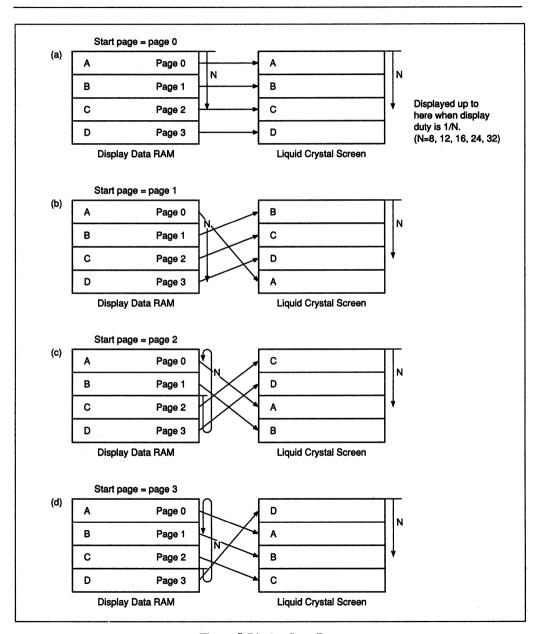


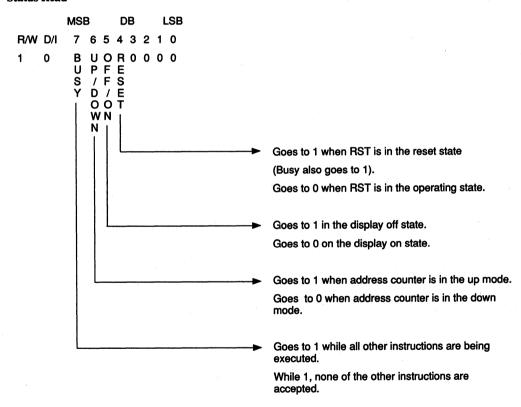
Figure 5 Display Start Page

# **Up/Down Set**

MSB			3	DB				ı	SE	3 .	
	R/W	D/I	7	6	5	4	3	2	1	0	
	0	0	0	0	1	1	1	0	1	1	Up mode
	0	0	0	0	1	1	1	0	1	0	Down mode

Sets Y address register in the up/down counter mode.

#### Status Read



# **Connection Between LCD Drivers (Example of 1/32 Duty Factor)**

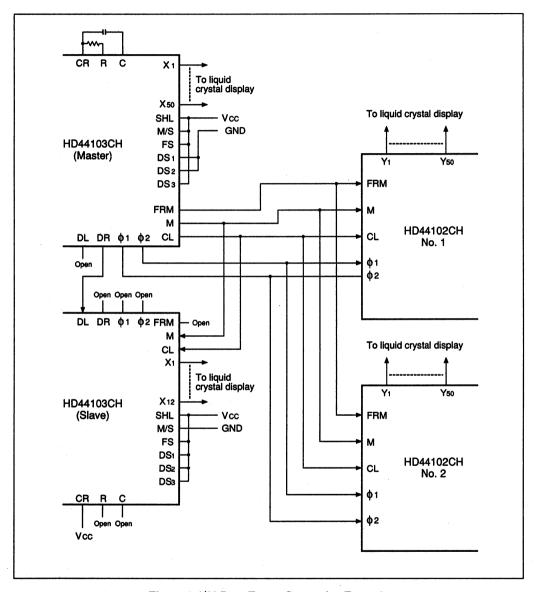


Figure 6 1/32 Duty Factor Connection Example

# **Interface to CPU**

# 1. Example of connection to HD6800

In the decoder given in this example, the addresses of

HD44102CH in the address space of HD6800 are:

Read/write of display data: \$'FFFF' Write of display instruction: \$'FFFE' Read of status: \$'FFFE' Thus, the HD44102CH can be controlled by reading/ writing data at these addresses.

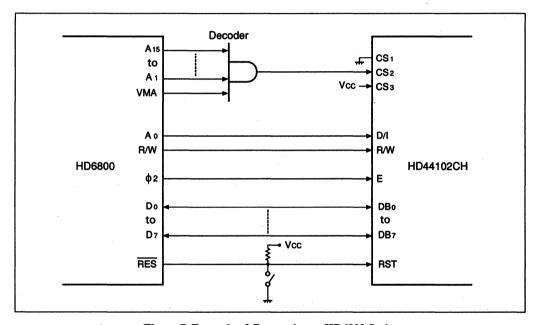


Figure 7 Example of Connection to HD6800 Series

#### 2. Example of connection to HD6801

- The HD6801 is set to mode 5. P10-P14 are used as output ports, and P30-P37 are used as the data bus.
- The 74LS154 is a 4-to-16 decoder that decodes 4 bits of P10-P13 to select the chips.
- Therefore, the HD44102CH can be controlled by selecting the chips through P10-P13 and specifying the D/I signal through P14 in advance, and later
- conducting memory read or write for external memory space \$0100 to \$01FF of HD6801. The IOS signal is output to SC1, and the R/W signal is output to SC2.
- For further details on HD6800 and HD6801, refer to their manuals.

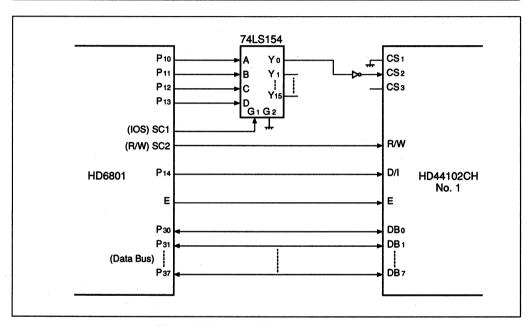


Figure 8 Example of Connection to HD6801

# **Connection to Liquid Crystal Display**

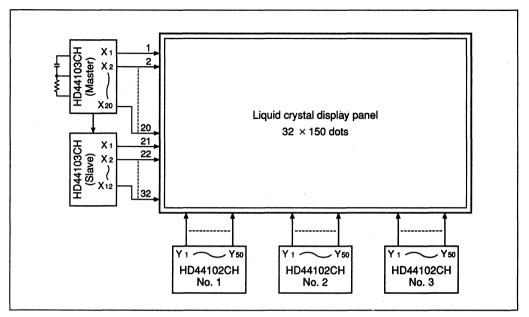


Figure 9 Example of Connection to 1/32 Duty Factor, 1-Screen Display

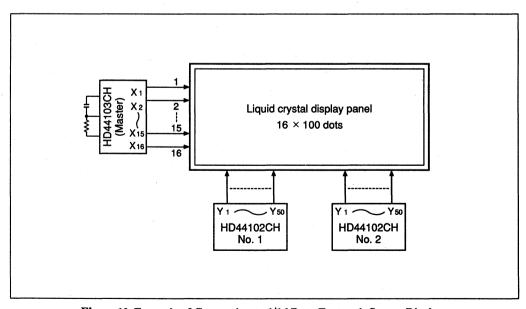


Figure 10 Example of Connection to 1/16 Duty Factor, 1-Screen Display

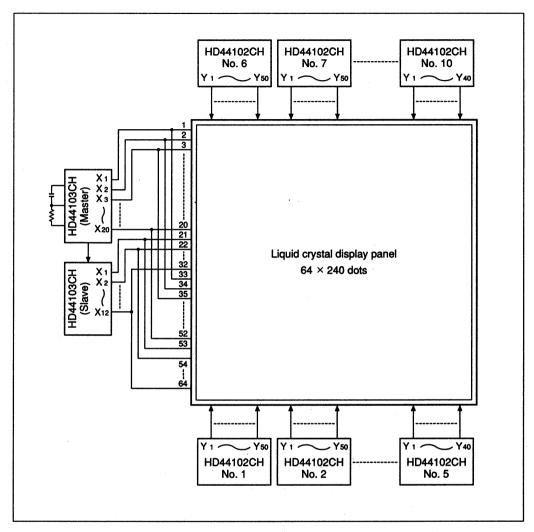


Figure 11 Example of Connection to 1/32 Duty Factor, 2-Screen Display

#### **Limitations on Using 4-Bit Interface Function**

The HD44102 usuallly transfers display control data and display data via 8-bit data bus. It also has the 4-bit interface function in which the HD44102 transfers 8-bit data by dividing it into the high-order 4 bits and the low-order 4-bits in order to reduce the number of wires to be connected. You should take an extra care in using the application with the 4-bit interface function since it has the following limitations.

#### Limitations

The HD44102 is designed to transfer the highorder 4-bits and the low-order 4-bits of data in that order after busy check. The LSI does not work normally if the signals are in the following state for the time period (indicated with (\*) in fifure 11) from when the high-order 4 bits are written (or read) to when the low-order 4 bits are written (or read); R/W = high and D/I = low while the chip is being selected (CS1 = high and CS2 = CS3 = don't care, or CS1 = low and CS2 = CS3 = high).

If the signals are in the limited state mentioned before for the time period indicated with (\*) the LSI does not work normally. Please do not make the signals indicated with dotted lines simultaneously. As far as the time period indicated with (\*\*), there is no problem.

The following explains how the malfunction is caused and gives the measures in application.

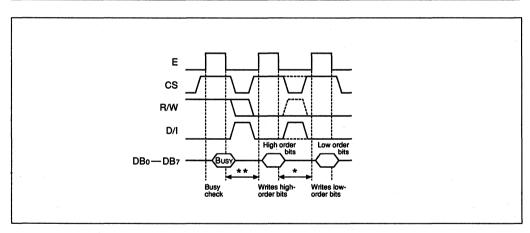


Figure 12 Example of Writing Display Control Instructions

#### Cause

Busy check checks if the LSI is ready to accept the next instruction or display data by reading the status register to the HD44102. And at the same time, it resets the internal counter counting the order of high-order data and low-order data. This function makes the LSI ready to accept only the high-order data after busy check. Strictly speaking, if R/W = high and D/I = low while the chip is being selected, the internal counter is reset and the LSI gets ready to accept high-order bits. Therefore, the LSI takes low-order data for high-order data if the state mentioned above exist in the interval between transferring high-order data and transferring low-order data.

#### Measures in Application

#### 1. HD44102 Controlled Via Port

When you control the HD44102 with the port of a single-chip microcomputer, you should take care of the software and observe the limitations strictly.

#### 2. HD44102 Controlled Via Bus

#### a. Malfunction Caused by Hazard

Hazard of input signals may also cause the phenomenon mentioned before. The phase shift at transition of the input signals may cause the malfunction and so the AC characteristics must be carefully studied.

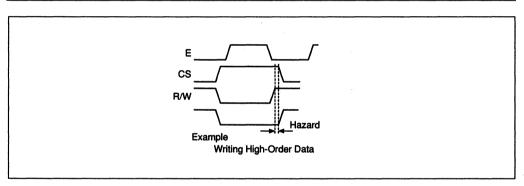


Figure 13 Input Hazard

#### b. Using 2-Byte Instruction

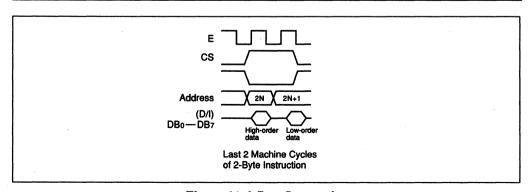


Figure 14 2-Byte Instruction

In an application with the HD6303, you can prevent malfunction by using 2-byte instructions such as STD and STX. This is because the high-order and low-order data are accessed in that order without a break in the last machine cycle of the instruction and R/W and D/I do not change in the meantime. However, you cannot use the least significant bit of the address signals as the D/I signal since the address for the

second byte has an added 1. Design the CS decoder so that the addresses for the HD44102 should be 2N and 2N + 1, and that those addresses should be accessed when using 2-byte instructions. For example, in figure 14 the address signal  $A_1$  is used as D/I signal and  $A_2 - A_{15}$  are used for the CS decoder. Addresses 4N and 4N + 1 are for instruction access and addresses 4N + 2 and 4N + 3 are for display data access.

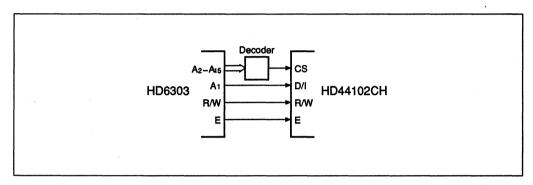


Figure 15 HD6303 Interface

# (Dot Matrix Liquid Crystal Graphic Display Common Driver)

# Description

The HD44105H is a common signal driver for LCD dot matrix graphic display systems. It generates the timing signals required for display with its internal oscillator and supplies them to the column driver (HD44102H) to control display, also automatically scanning the common signals of the liquid crystal according to the display duty cycle. It can select 7 types of display duty cycle 1/8, 1/12, 1/16, 1/24,1/32, 1/48, and 1/64. It provides 32 driver output lines and the impedance is low (1 k $\Omega$  max) enough to drive a large screen.

#### **Features**

- Dot matrix graphic display common driver including the timing generation circuit
- Internal oscillator (Oscillation frequency is selectable by attaching an oscillation resistor and an oscillation capacitor)
- · Generates display timing signals
- 32-bit bidirectional shift register for generating common signals
- 32 liquid crystal driver circuits with low impedance
- Selectable display duty ratio: 1/8, 1/12, 1/16, 1/24, 1/32, 1/48, 1/64
- Low power dissipation
- Power supplies:  $V_{CC} = +5 \text{ V} \pm 10\%$  $V_{EE} = 0 \text{ to } -5.5 \text{ V}$
- CMOS process

# **Ordering Information**

Type No.	Package
HD44105H	60-pin plastic QFP(FP-60)
HD44105D	Chip

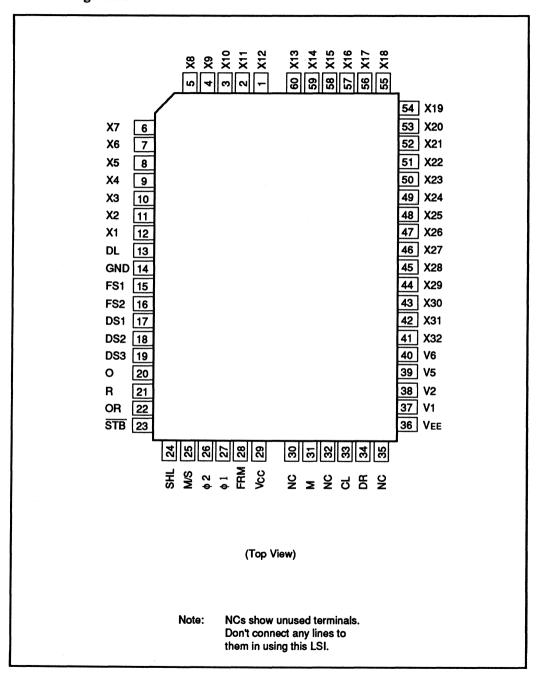
# Absolute Maximum Rating (Ta =25°C)

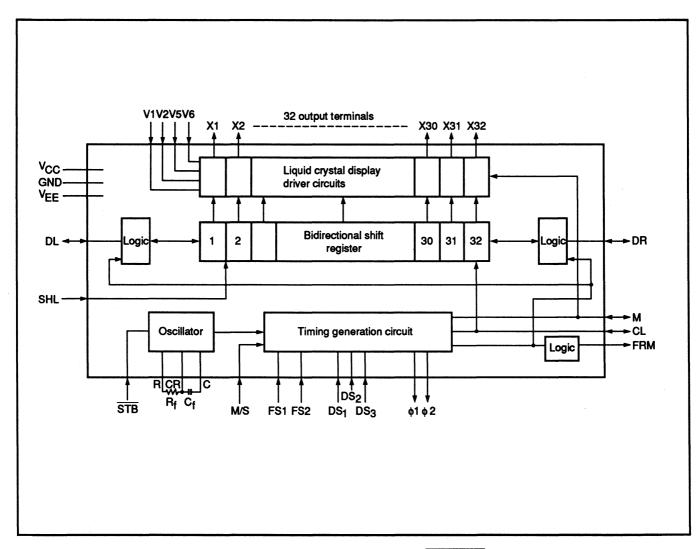
Item	Symbol	Ratings	Unit	Note
Supply voltage (1)	V <sub>CC</sub>	-0.3 to +7.0	٧	1
Supply voltage (2)	V <sub>EE</sub>	V <sub>CC</sub> -13.5 to V <sub>CC</sub> +0.3	٧	
Terminal voltage (1)	V <sub>T1</sub>	-0.3 to V <sub>CC</sub> +0.3	٧	1, 2
Terminal voltage (2)	V <sub>T2</sub>	V <sub>EE</sub> -0.3 to V <sub>CC</sub> +0.3	V	3
Operating temperature	Topr	-20 to +75	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1.

- Referred to GND = 0 V.
- 2. Applied to input terminals (except for V1, V2, V5, and V6) and I/O common terminals.
- 3. Applied to terminals V1, V2, V5, and V6. Connect a protection resistor of 47  $\Omega \pm$  10% to each terminal in series.

# Pin Arrangement



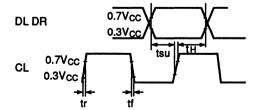


# Electrical Characteristics (Note 4) $(V_{CC} = +5 \ V \pm 10\%, \ GND = 0 \ V, \ V_{EE} = 0 \ to -5.5 \ V, \ Ta = -20 \ to +75^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition	Note
Input high voltage	V <sub>IH</sub>	0.7 × V <sub>CC</sub>		V <sub>CC</sub>	٧		5
Input low voltage	V <sub>IL</sub>	0	*****	0.3 × V <sub>CC</sub>	٧		5
Output high voltage	V <sub>OH</sub>	V <sub>CC</sub> -0.4			٧	I <sub>OH</sub> = -400 μA	6
Output low voltage	VOL	_		0.4	٧	l <sub>OL</sub> = 400 μA	6
Vi-Xj On resistance	R <sub>ON</sub>			1000	Ω	$V_{EE} = -5 V \pm 10\%$ , Load current $\pm 15 \mu A$	
Input leakage current (1)	l <sub>IL1</sub>	-1		1	μΑ	V <sub>IN</sub> = V <sub>CC</sub> to GND	7
Input leakage current (2)	l <sub>IL2</sub>	<b>-</b> 5		5	μΑ	$V_{IN} = V_{CC}$ to $V_{EE}$	8
Shift frequency	F <sub>SFT</sub>	_		50	kHz	In slave mode	9
Oscillation frequency	fosc	300	430	560	kHz	Rf = 68 k $\Omega$ ± 2%, Cf = 10 pF ± 5%	10
External clock operating frequency	f <sub>CP</sub>	50		560	kHz		11
External clock duty cycle	Duty	45	50	55	%		11
External clock rise time	trcp		_	50	ns		11
External clock fall time	tfCP	_	_	50	ns		11
Dissipation power (Master)	P <sub>W1</sub>			4.4	mW	CR oscillation, 430 kHz	12
Dissipation power (Slave)	P <sub>W2</sub>			1.1	mW	Frame 70 kHz	13

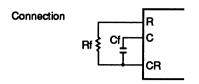
Notes: 4.

- 4. Specified within this range unless otherwise noted.
  - 5. Applied to CR, FS1, FS2, DS1 to DS3, M, SHL, M/S, CL, DR, DL, and STB.
  - 6. Applied to DL, DR, M, FRM, CL, φ1, and φ2.
  - 7. Applied to input terminals CR, FS1, FS2, DS1 to DS3, SHL, M/S, and STB and I/O common terminals DL, DR, M, and CL at high impedance.
  - 8. Applied to V1, V2, V5, and V6.
  - 9. Shift operation timing.

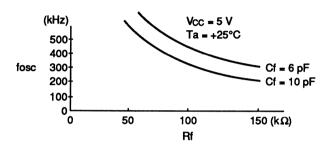


	Min	Тур	Max	Unit
tsu	5	-	-	μs
t <sub>H</sub>	5	_	_	μs
tr	_	_	100	ns
tf	-	_	100	ns

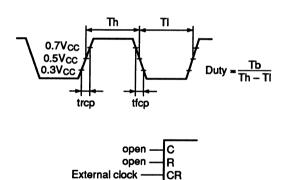
Notes: 10. Relation between oscillation frequency and Rf, Cf.



The values of Rf and Cf are typical values. The oscillation frequency varies with the mounting condition. Adjust oscillation frequency to a required value.



11.



- 12. Measured by Vcc terminal at output non-load of Rf = 68 k $\Omega$  ± 2% and Cf = 10 pF ± 5%, and 1/32 duty cycle in the master mode. Input terminals are connected to Vcc or GND.
- Measured by Vcc terminal at output non-load, 1/32 duty cycle, and frame frequency of 70 Hz in the slave mode.
   Input terminals are connected to Vcc or GND.

# Pin Description

Pin Name	Pin	Number	1/0	Function								
X1-X32	32		0	Liquid crysta Relation amo				data ([	D) in	shift reg	jister.	
					М		1			0		
					D	1		ο Г	1	_	οГ	
				Outp	out level		  -	V6 .	V1	 ' '	/5	
						<u> </u>	!	t			1	
CR, R, C	3			Oscillator.	Rf Cf 		R Oscil	lator				
M	1		1/0	Signal for co	nverting	g liquid c	rystal d	isplay d	lriver	signal i	into AC.	
				Master: Slave:	Out	put termi at termina	nal			J		
aL .	1		1/0	Shift registe	r shift c	lock.						
				Master:	Out	put termi	nai					
				Slave:	Inpu	t termina	al					
FRM	1		0	Frame signa	l, Displ	ay synch	ronous	signal.				
DS1-DS3	3		1	Display duty	ratio s	elect.						
				Display Duty Ratio	1/8	. 1/16	1/32	1/64	_	1/12	1/24	1/48
				DS1	L	L	Н	Н	L	L	Н	Н
				DS2	L	Н	L	Н	L	Н	L	Н
			*****	DS3	L	L	<u>L</u>	<u> </u>	Н	Н	Н	H
FS1-FS2	2		1	Selects freq	uency.							
				The relation frequency fo				uency f	FRM 8	and the	oscillati	on
				FS1 FS2	fo	sc(kHz)	fFF	RM(Hz)	1	f <sub>M</sub> (Hz)	fcp(	kHz)
				L L	10	7.5	70	1	;	35	53.8	3
				H L	10	7.5	70	l	;	35	53.8	3
				L H	21	5.0	70			35	107	.5
				<u>H H</u>	43	0.0	70			35	215	.0
			NANESSAINAS UN SUURIANS SAINAS SA	fosc: Oscillation frequency fFRM: Frame frequency fM: M signal frequency fcp: Frequencies of \$\phi\$1 and \$\phi\$2								

# Pin Description (cont)

Pin Name	Pin Number	1/0	Function						
STB	1	ı	Input terminal for testing.						
			Connect this terminal to Vcc.						
DL, DR	2	1/0	Data I/O terminals of bidirectional shift register.						
SHL	1	1	Selects shift direction of bidirectional shift register.						
			SHL Shift Direction						
			H DL→DR						
			L DL←DR						
M/S	1	ľ	Selects Master/Slave.						
			M/S = High: Master mode The oscillator and timing generation circuit operate to supply display timing signals to the display system. Each of I/O common terminals, DL, DR, M, and CL is in the output state.						
			M/S = Low: Slave mode  The timing generation circuit stop operating. The oscillator is not required. Connect terminal CR to Vcc. Open terminals C and R.  One (determined by SHL) of DL and DR, and terminals M and CL are in the input state. Connect M, CL and one of DL and DR of the master to the respective terminals. Connect FS1, FS2, DS1, DS2 DS3, STB to Vcc. When display duty ratio is 1/8, 1/12, 1/16, 1/24 1/32, one HD44105H is required. Use it in the master mode. When display duty ratio is 1/48, 1/64, two HD44105Hs are required. Use one in the master mode to drive common signals 1 to 32, and another in the slave mode to drive common signals 33 to 48(64).						
φ1, φ2	2	0	Operating clock output terminals for HD44102CH. The frequencies of \$\phi\$1 and \$\phi\$2 are half of oscillation frequency.						
V1, V2,	4		Liquid crystal display driver level power supply.						
V5, V6			V1 and V2: Selected level V5 and V6: Non-selected level						
V <sub>CC</sub> , GND	3		Power supply.						
V <sub>EE</sub>			VCC – GND: Power supply for internal logic VCC – VEE: Power supply for driver circuit logic						

#### **Block Functions**

#### Oscillator

A CR oscillator attached to an oscillation resistor Rf and an oscillation capacitor Cf. The oscillation frequency v aries with the values of Rf and Cf and the mounting conditions. Refer to electrical characteristics (note 10) to make proper adjustment.

# **Timing Generation Circuit**

This circuit divides the signals from the oscillator and generates display timing signals (M, CL, and FRM) and operating clock ( $\phi$ 1 and  $\phi$ 2) for HD44102CH according to the display duty ratio set by DS1 to DS3. In the slave mode, this block stops operating. It is meaningless to set FS1, FS2 and DS1 to DS3. However, connect them to  $V_{CC}$  to prevent floating current.

## Bidirectional Shift Register

A 32-bit bidirectional shift register. The shift direction is determined by the SHL. The data input from DL or DR performs a shift operation at the rise of shift clock CL.

## Liquid Crystal Display Driver Circuit

Each of 32 driver circuits is a multiplex circuit composed of four CMOS switches. The combination of the data from the shift register with the M signal allows one of the four liquid crystal display driver levels V1, V2, V5, and V6 to be transferred to the output terminals.

HITACHI

Connection

between

HD44105H

and

**HD44102CH** 

